

TRENDS AND CHALLENGES IN AUTOMOTIVE INFOTAINMENT

MARK FITZGERALD STRATEGY ANALYTICS ASSOCIATE DIRECTOR – AUTOMOTIVE PRACTICE

PUBLIC USE



DAVE CHENEY

GM Infotainment Hardware

PUBLIC USE **#NXPFTF**

1

"The automotive industry will change more in the next 5 to 10 years than in the last 50"

- Mary Barra, General Motors CEO



CONNECTIVITY IS A FOUNDATIONAL ENABLER FOR MANY GM INITIATIVES







Solutions delivered by multiple methods







SINCE FOUNDED 19 YEARS AGO

>99% of customers agree to the terms to have their vehicles connected



>50 MILLION RemoteLink interactions in first half of 2015



~1 MILLION 4G LTE enabled vehicles











COMPLEXITY YING AND BANG

ALAN NORTON, FORD MOTOR COMPANY SENIOR TECHNICAL LEADER, AUDIO SYSTEMS



PUBLIC USE



ALAN NORTON

- Joined Ford in 1990
 - Early navigation projects
 - Body & security products
- Visteon 1998 2004
 - Multiple J-OEM projects
 - Interior & Electronics lead for Ford C-MAX & Focus
- Joined Ford Of Germany 2004
 - European Upper Body Electronics, Global HMI Lead
 - Global Entertainment Electronics
 - Senior Technical Leader, Audio Systems







COMPLEXITY IS EASY, ISN'T IT?

- Design and build a super integrated module that covers all your in vehicle infotainment needs
- Leverage enormous volume to achieve lowest cost
- Provide flexibility by software configurable features





COMPLEXITY BANG! WHAT EVERY INFOTAINMENT TEAM IS DEALING WITH!

- My program can't afford the overhead, create a version with less memory, channels, tuners...
- Let's put this into three legacy vehicles, make three new bracket variants
- We need supplier competition, key design aspects are supplier IP, rewrite some of the software
- Package in a hot location, add a fan





COMPLEXITY BANG! WHAT EVERY INFOTAINMENT TEAM IS DEALING WITH!





SEE IT'S EASY!

Thank You





TRENDS AND CHALLENGES IN AUTOMOTIVE INFOTAINMENT

MARK FOSMOEN VISTEON N. AMERICA ENGINEERING DIRECTOR

PUBLIC USE

Visteon at a Glance





Visteon at a Glance: Product/Technical Landscape

R&D more than 30% of global workforce





1,600R&D

employees develop

Software

Abstract Interest: Summary

Interest Scope: We see growing demand for aggressive implementation timing and content

- Most notably are the increases in:
 - Display resolution, luminance, processor demands (due to UI requirements and data handling) and inter-module communication
 - These needs have caused integration challenges
- Potential Growth in Domain Integration.
 - Integration of Cluster, ADAS and Infotainment for cost and inter-module communication optimization
 - Results in complexity management concerns for entry systems
- Challenge Areas:
 - X-OEM customer Re-use of core assets
 - Thermal management
 - EMC management
 - Distributed system architectures: Well defined inter-module (network) communication.



Abstract Interest: Challenge Areas (expanded):

- X-OEM customer Re-use of core assets:
 - Tier 1's need to develop re-usable assets x-customer and across HW platforms
 - One solution model is to partition the SW and HW "stable" assets on a low overhead uP/OS that has maximum HW abstraction and SW that tends to be only configured by OEM (not fully custom)
 - For multiple Micro based solutions:
 - Network, Diagnostics, Core functions like Tuner controls (audio), Cluster core Application code (DI) and power state handling to be done on ViP. Preferable in an AutoSar environment to help configure/abstract from the HW.
 - The GP (graphics processor) to be used for "Unstable" functions such as UI, Connectivity, high bandwidth network interfaces such as MOST150 and Ethernet
- Thermal management:
 - Display sizes/brightness:
 - 1000nits is not an uncommon requirement (to the user) for displays that are not shrouded
 - We are targeting illumination sources that can supply 1.5X the visible targets
 - SoC thermal management:
 - Most of our SoCs need DIRECT passive or active thermal management by Tier1
 - These are adding cost, weight, size and EMC noise that we need to manage in design





Abstract Interest: Challenge Areas (expanded):

- EMC management:
 - Growth in the SoC, Memory, and content within the constrained package we are delivered, resulting in most Tier1's having to move to higher PWB layer counts as well as creative ways to shield their module (RE and RI)
 - Chassis or Die Cast housing serving dual purposes for Thermal and EMC management (heatsink + Faraday cage)
- Distributed system architectures:
 - As several OEMs move to greater distribution of functions, another challenge is data management between modules via MOST150, Ethernet, or lower bandwidth interfaces without pre-defined messaging
 - Non-standard use cases and inter-module handling of these fringe use cases are normally weak areas of timing specs
 - Tends to take system level testing to resolve late in programs due to need for module maturation

Take Away: Recognition of the Timing, Weight and Cost impacts of Technology Growth Management need to be planned for in the Development Cycle





TRENDS AND CHALLENGES IN AUTOMOTIVE INFOTAINMENT

IVAN DZOMBAK CHIEF ENGINEER, INFOTAINMENT SYSTEMS, HARMAN

PUBLIC USE

ABOUT HARMAN



• **\$6.2** Billion revenues* *Last 12 Months as June 30, 2015.

MARKET LEADER



- 27,000 Professionals worldwide
- 12,600 Engineers
- 25+ Countries: Americas, Europe and Asia
- 16+ Legendary brands

GLOBALLY DIVERSE





- 5,700 Patents and patents pending
- 51 Design awards in 2014
- 3 GRAMMY® Awards-AKG, JBL, Lexicon
- 2 Academy Awards

INNOVATION LEADER



ABOUT HARMAN

CONNECTED CARLIFESTYLE AUDIOPROFESSIONAL SOLUTIONSCONNECTED SERVICESImage: transformation of tr

Navigation, Multimedia, Connectivity, Telematics, Safety & Security Solutions

Premium Branded Audio products for use at home, in the car and on the go

Audio, Lighting, Video Switching and Enterprise Automation for Entertainment and Enterprises

Cloud, Mobility and Analytics Software Solutions along with OTA update technologies for Automotive, Mobile and Enterprises





Automotive Infotainment Trends and Challenges

Trend / Market Demand	Challenges
Compressed schedules	Getting the product defined quickly enoughMeeting quality goals for software and hardware
More features	 Drives software and testing complexity May confuse users if not presented intuitively Usually increases hardware requirements, packaging density, and power dissipation
Robust security	 Conflicts with trend toward more connectivity and keeping the software "fresh" Complicates development, manufacturing, and testing
Function consolidation, including safety functions	 Adds complexity to reach the desired level of safety Physical I/O and connector space limitations
Higher-resolution displays and more of them	 Dramatic increase in memory bandwidth Automotive digital video interfaces are lagging consumer interfaces Thermal management



Automotive Infotainment Trends and Challenges

Trend / Market Demand	Challenges
Digital camera interfaces and more of them	 Physical I/O limitations Memory bandwidth Image signal processing (ISP) requirements
Latest wireless consumer interfaces	 MIMO → more antennae Packaging constraints → antenna locations? Host processor I/O loading
Latest wired consumer interfaces (Especially USB Type C)	 Cable lengths that vary by vehicle Signal integrity / standards compliance issues IR drop for high-current charging modes Protection for data lines conflicts with signal integrity
Projection mode support (CarPlay, Android Auto, Baidu CarLife)	Need to support USB device mode and role switchingIncreased hub complexity
State-of-the-art processing, graphics, and memory	 Reduced Tj(max) for state-of-the-art SOCs More difficult memory interface and power distribution network design





SECURE CONNECTIONS FOR A SMARTER WORLD